



WI 300 Wafer Inspection Machine is designed to deliver utmost flexibility to support top vision inspection for fabricated components on wafer such as lens, LED & IC packages from 4" tiles to 8" wafer.

With unique blend of flexibility and high performance, it makes an ideal inspection solution for automation industry.

- Equipped with high resolution camera with selection from 5MP to 25MP mono/ color camera imaging technology
- Integrated several techniques such as color inspection, normalized correlation and rule based algorithms
- Offers software alignment function to adjust wafer alignment angle for top vision inspection
- Real time wafer map display. All inspection information like mapping map, defect region, inspection results is visualized for easy reading.
- Support common wafer map output format such as STIF files.
- SPC statistical tool to monitor yield trend / defect breakdown.
- Minimum detectable defect size 15 μm x 15
- Inspection criteria including marking, surface cosmetic, fresnel inspection, mix device, contamination, chipping, cracked, foreign material, scratches, wire bond etc.
- Confocal displacement sensor for warpage detection. Height compensation up to 2mm.



Products :	LED Chip, wafer chip, IR sensor, laser diode	
Specification	Input :	Tiles, wafer, wafer rings
	Output :	Tiles, wafer, wafer rings
UPH :	40K	
MTBA :	60 minutes	
Vision Inspection	Cosmetics and measurement	

Foot Print	1300mm x 1230mm x 2100mm
Facilities	Power : 208VAC 50/60Hz (Three phase + Neutral) Air Pressure : 0.5 Mpa
Warranty	1 year limited, excluding wear and tear parts